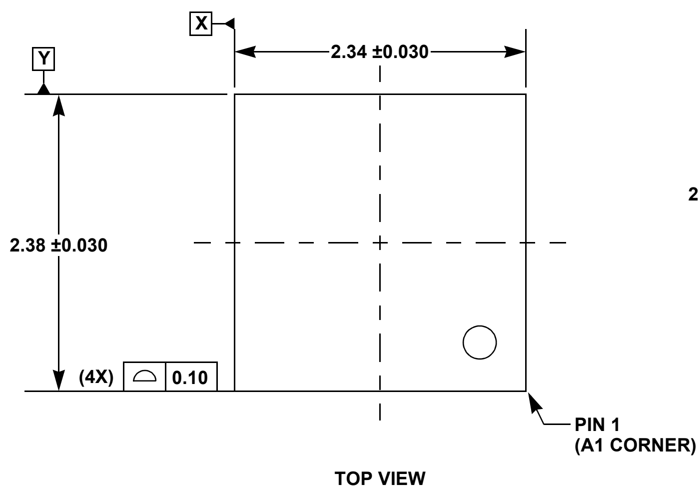
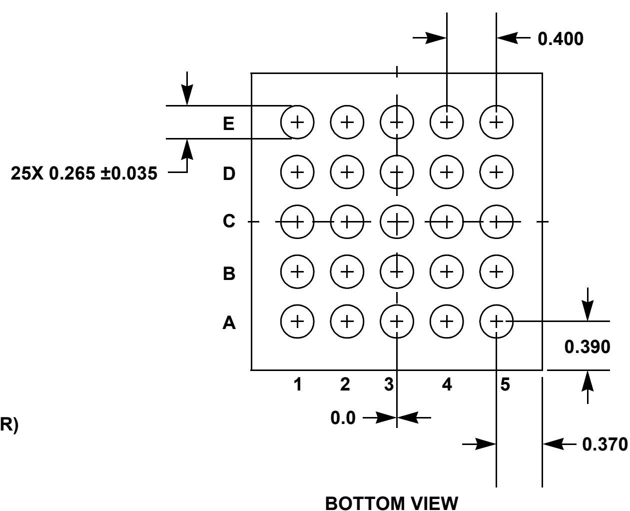
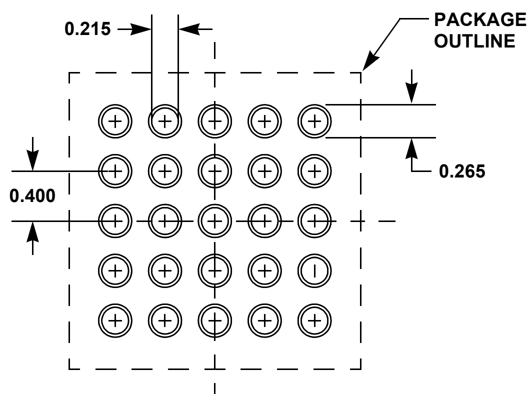
Package Outline Drawing

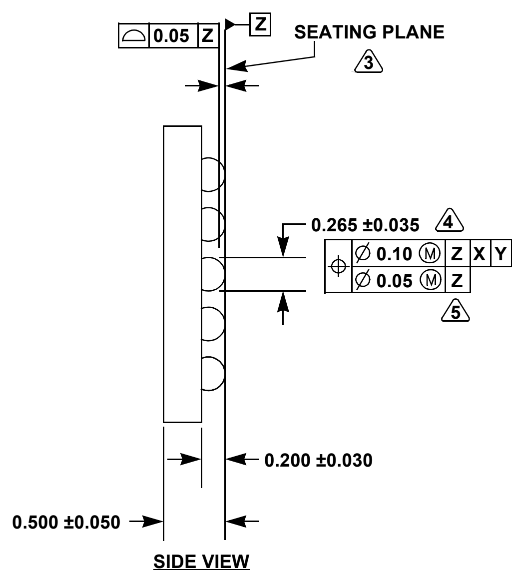
W5x5.25G

5x5 ARRAY 25 BALLS WITH 0.4mm PITCH WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)
Rev 0, 12/16









NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASME Y14.5M - 1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.